

MECHANICAL CASE OUTLINE

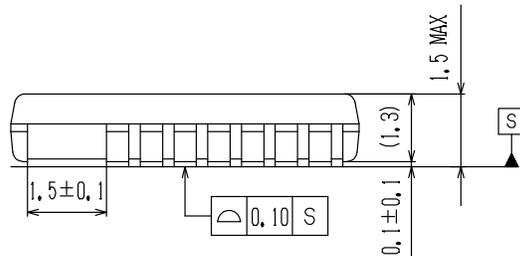
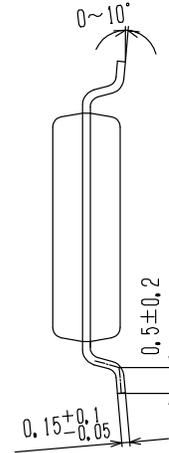
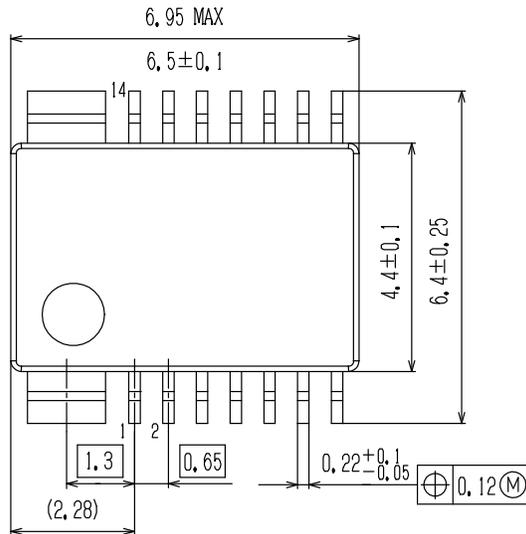
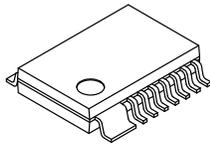
PACKAGE DIMENSIONS

ON Semiconductor®

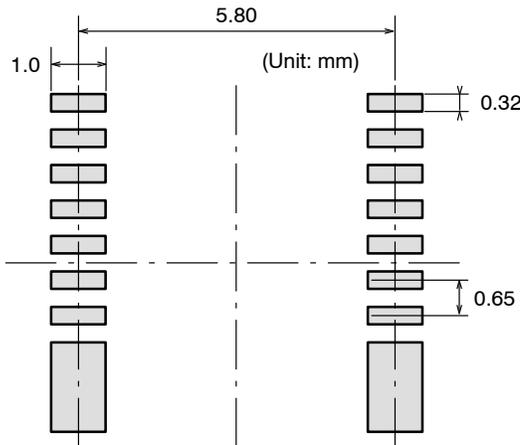


HSSOP14 (225mil) CASE 944AA ISSUE A

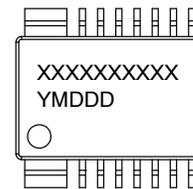
DATE 23 OCT 2013



SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

NOTES: 1. The measurements are not to guarantee but for reference only.
2. Land pattern design in Fin area to be altered in response to customer's individual application.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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